

U.S. CHIPS Act funding for Texas Instruments



PROPOSED DIRECT FUNDING

\$1.6 billion

for the construction of three wafer fabs in Texas and Utah

ESTIMATED INVESTMENT TAX CREDIT

~\$6-8 billion

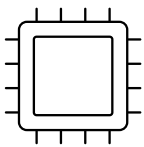
benefit for all qualified U.S. manufacturing investments

WORKFORCE DEVELOPMENT GRANT

\$10 million

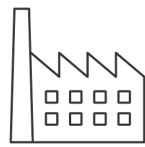
to train and develop a skilled workforce

Building the next era of semiconductor manufacturing



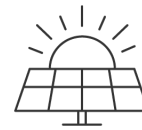
CREATING A BETTER WORLD

100s of millions of analog and embedded processing chips manufactured daily



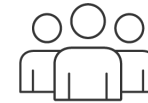
DEPENDABLE 300MM CAPACITY

28-180nm process technologies optimized for TI's broad portfolio



POWERED SUSTAINABLY

300mm wafer fabs powered by 100% renewable electricity



DEVELOPING A STRONG WORKFORCE

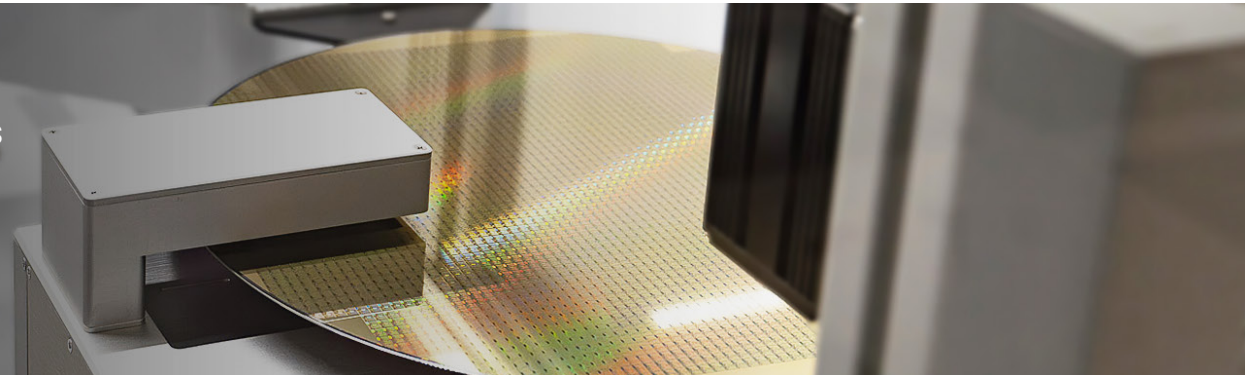
2,000+ new TI jobs and 1,000s of indirect jobs; 40 academic, military and vocational engagements

TI's 300mm wafer fab manufacturing

Providing geopolitically dependable, 300mm semiconductor capacity at scale

Connected, large-scale wafer fabs

- State-of-the-art infrastructure and processes
- Operational efficiencies
- Talent and technology sharing
- Robust business continuity



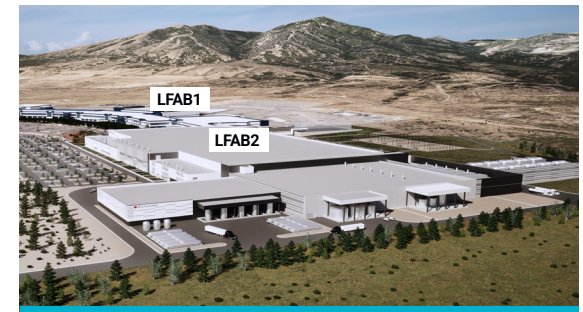
Richardson, Texas

TI opened the world's first 300mm analog wafer fab, RFAB1, in Richardson in 2009, a few miles north of the company's headquarters in Dallas. TI added a second 300mm wafer fab, RFAB2, that is connected to RFAB1. These two fabs will produce more than 100 million analog chips every day.



Sherman, Texas

Building on a 70+ year history in Sherman, TI plans to build up to four new 300mm wafer fabs with 1.3 million square feet of cleanroom space. The first two fabs, SM1 and SM2, are currently under construction. First production from SM1 is expected as early as 2025.



Lehi, Utah

In 2021, TI purchased a 300mm wafer fab, LFAB1, located in Lehi. LFAB1 started producing analog and embedded chips on 45nm and 65nm process technologies, and is now developing 28nm technology. TI is building a second 300mm fab, LFAB2, which will connect to LFAB1.